

MT18SD-H

- Micro Thin為附18 μ m載體銅箔的超薄銅箔。
Micro Thin is ultra thin foil with 18 μ m carrier foil.
- 最適用於線寬/線距(L/ S)=25/25~40/40之應用。
Usable for fine pitch pattern L/S=25/25 – 40/40 formation.

用途/Application

- IC封裝載坂
/Semiconductor Package

構成/Composition



生產地點/Production Site

- 日本 / Japan

代表性特性數據/Representative

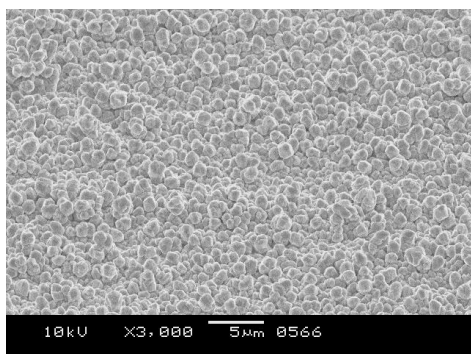
	μ m	Laminate side Rz(μ m)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm)@FR-4
MT18SD-H	3	3	—	—	1.4
	5	3	—	—	1.4

※上述表列為代表性數據非保證值

This is representative data, not guarantee.

※Peel Strength為增鍍到35 μ m厚度之後的測試值
Evaluated after plated up to 35 μ m.

處理面/Laminate side



阻劑面/ resist side

